

Title (en)
METHOD FOR APPLYING AN ELECTRICAL MICROSTRUCTURE, ELASTOMER STRUCTURE, FIBER COMPOSITE COMPONENT, AND TIRE

Title (de)
VERFAHREN ZUR ANBRINGUNG EINER ELEKTRISCHEN MIKROSTRUKTUR SOWIE ELASTOMERSTRUKTUR, FASERVERBUNDBAUTEIL UND REIFEN

Title (fr)
PROCÉDÉ DE DÉPÔT D'UNE MICROSTRUCTURE ÉLECTRIQUE AINSI QUE STRUCTURE ÉLASTOMÈRE, ÉLÉMENT COMPOSÉ DE FIBRES ET PNEU

Publication
EP 3552464 A1 20191016 (DE)

Application
EP 17805160 A 20171121

Priority
• DE 102016123795 A 20161208
• EP 2017079938 W 20171121

Abstract (en)
[origin: WO2018104047A1] The invention relates to a method for applying an electrical microstructure on or in an object of any type, wherein the electrical microstructure is first applied to a flexible film and the film is fastened, with the electrical microstructure applied thereto in front, to a fastening surface of the object by adhesive bonding and/or vulcanization attachment. The invention further relates to an elastomer structure, to a fiber composite component, and to a motor-vehicle tire, each having at least one electrical microstructure fastened thereto by adhesive bonding and/or vulcanization attachment.

IPC 8 full level
H05K 3/02 (2006.01)

CPC (source: EP US)
B60C 23/0493 (2013.01 - US); **H05K 1/181** (2013.01 - US); **H05K 3/025** (2013.01 - EP); **H05K 3/303** (2013.01 - US); **H05K 2201/0317** (2013.01 - EP US); **H05K 2203/0156** (2013.01 - EP US); **H05K 2203/0264** (2013.01 - EP US); **H05K 2203/0773** (2013.01 - EP)

Citation (search report)
See references of WO 2018104047A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
WO 2018104047 A1 20180614; CN 110073727 A 20190730; DE 102016123795 A1 20180614; EP 3552464 A1 20191016; JP 2020501350 A 20200116; US 2020068718 A1 20200227

DOCDB simple family (application)
EP 2017079938 W 20171121; CN 201780075949 A 20171121; DE 102016123795 A 20161208; EP 17805160 A 20171121; JP 2019527533 A 20171121; US 201716466472 A 20171121